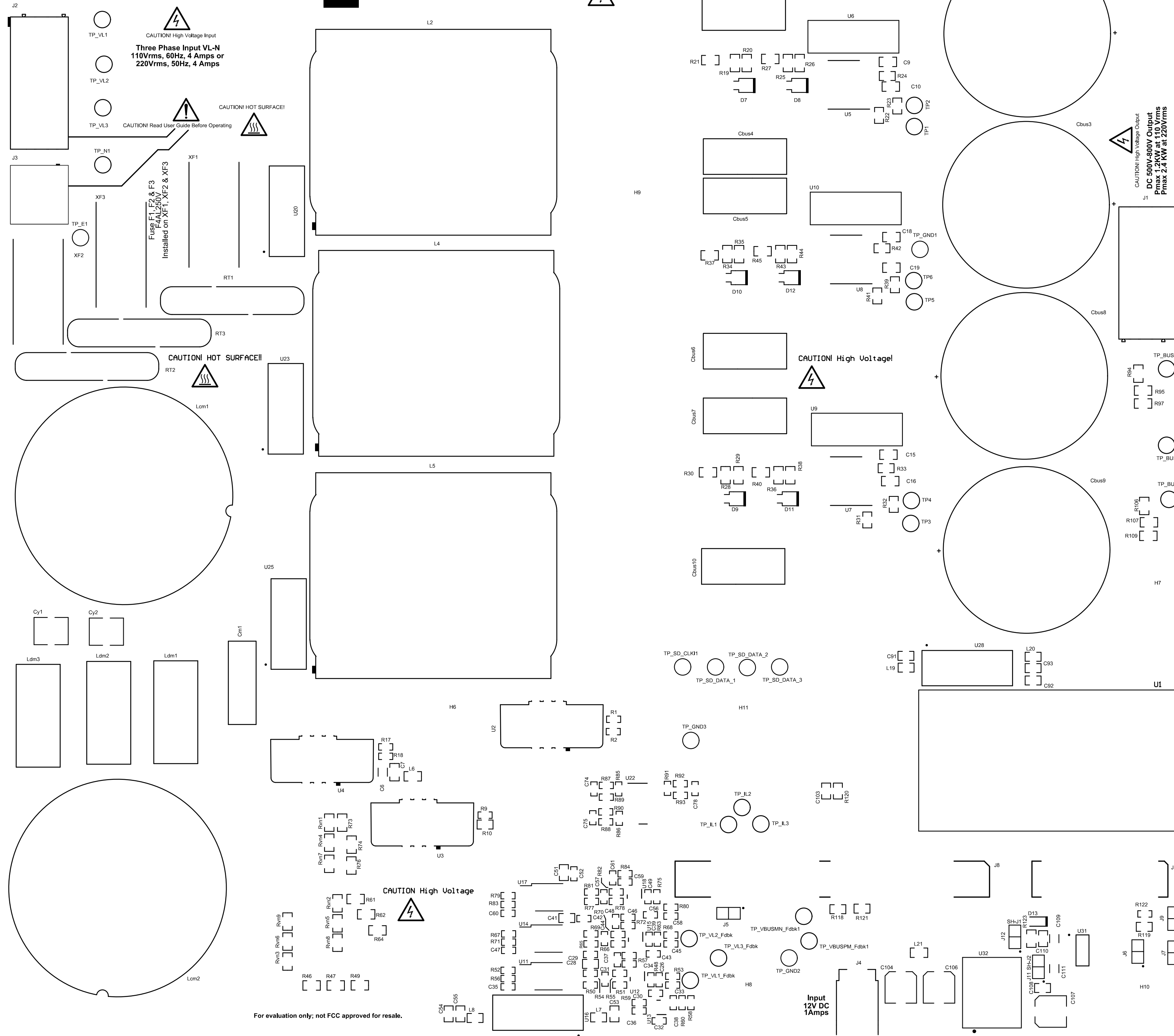


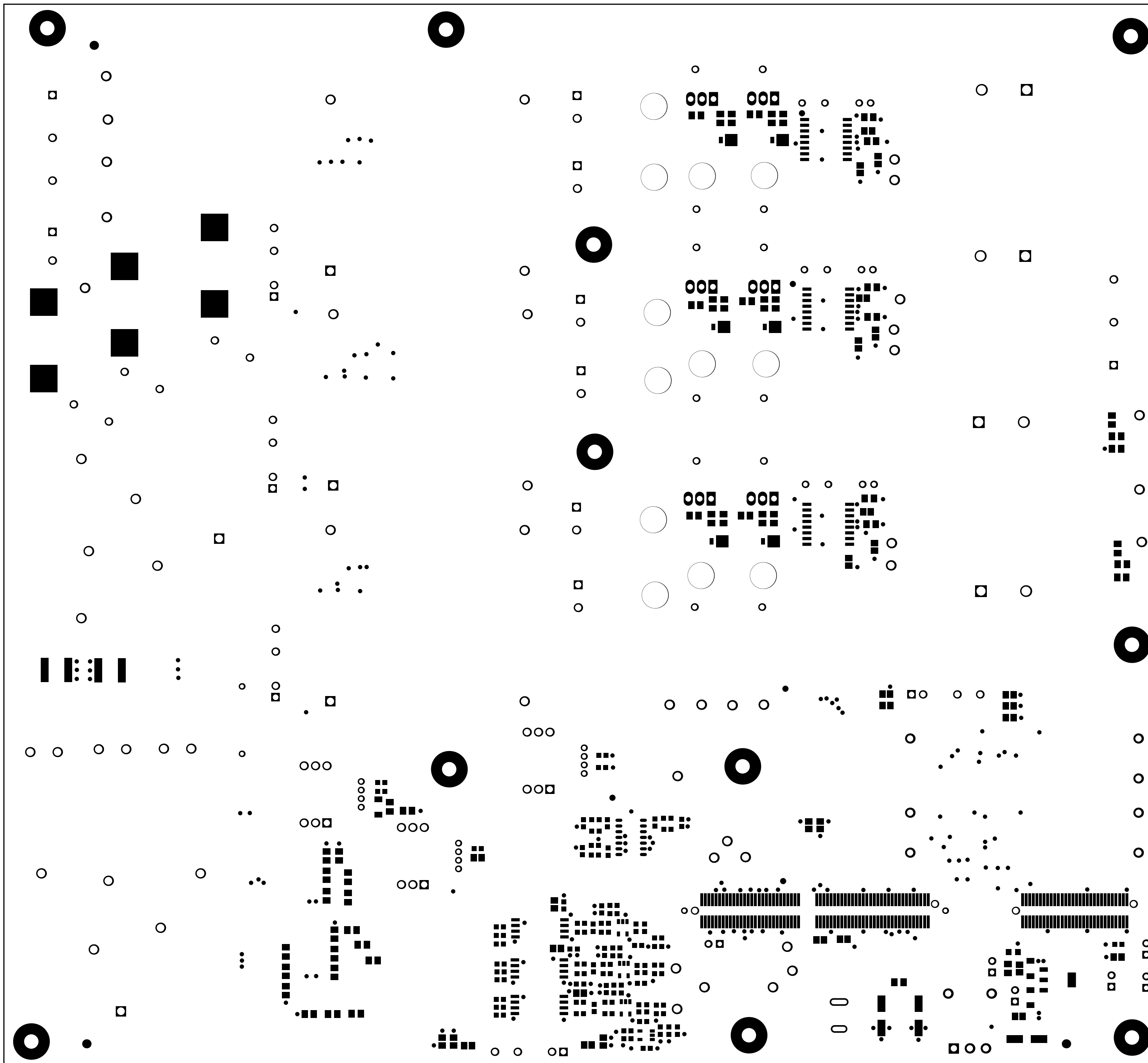
CAUTION! High Voltage

C2000 MCU THREE PHASE VIENNA RECTIFIER BOARD TIEVM-VIENNA RECT

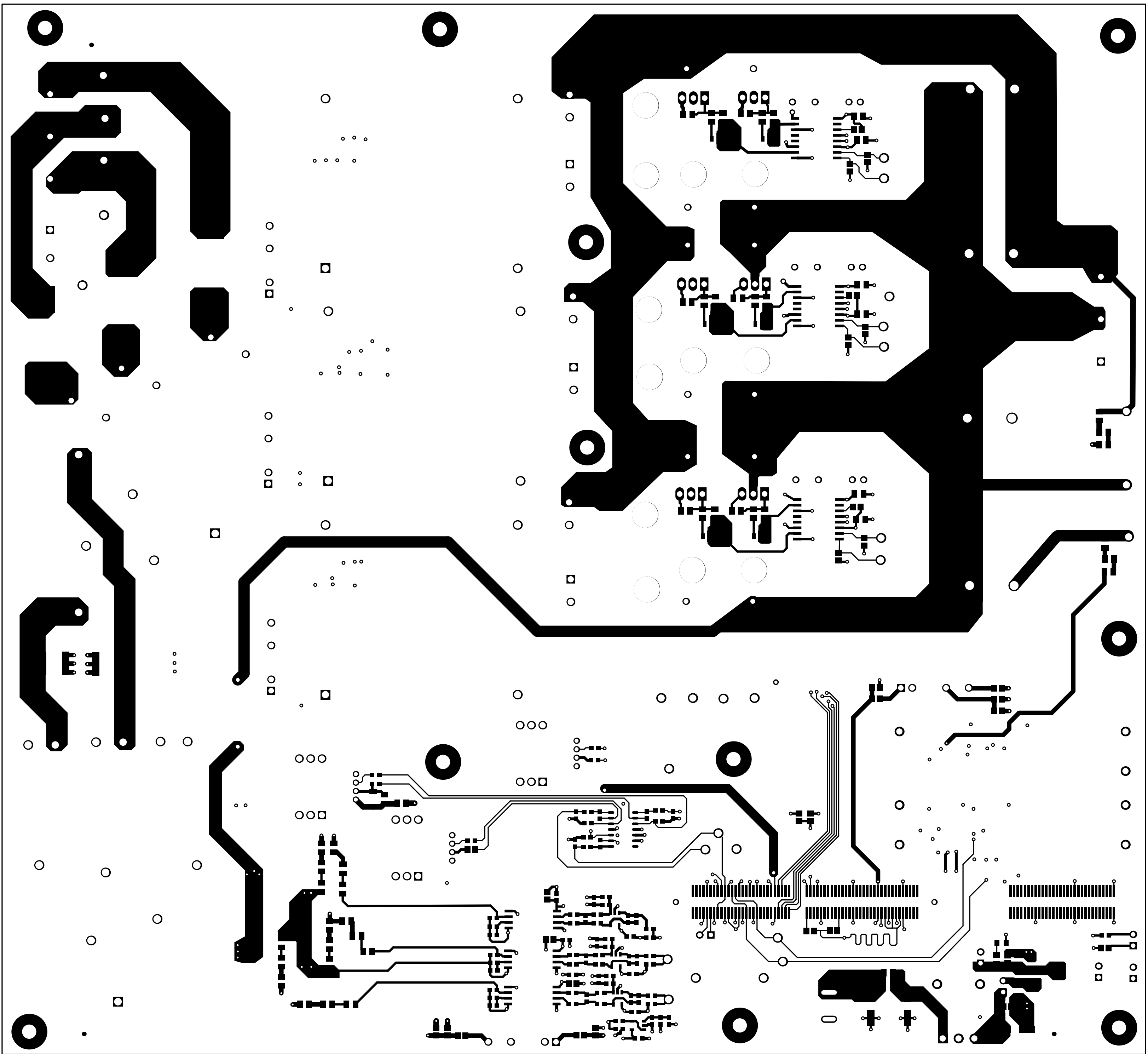


For evaluation only; not FCC approved for resale.

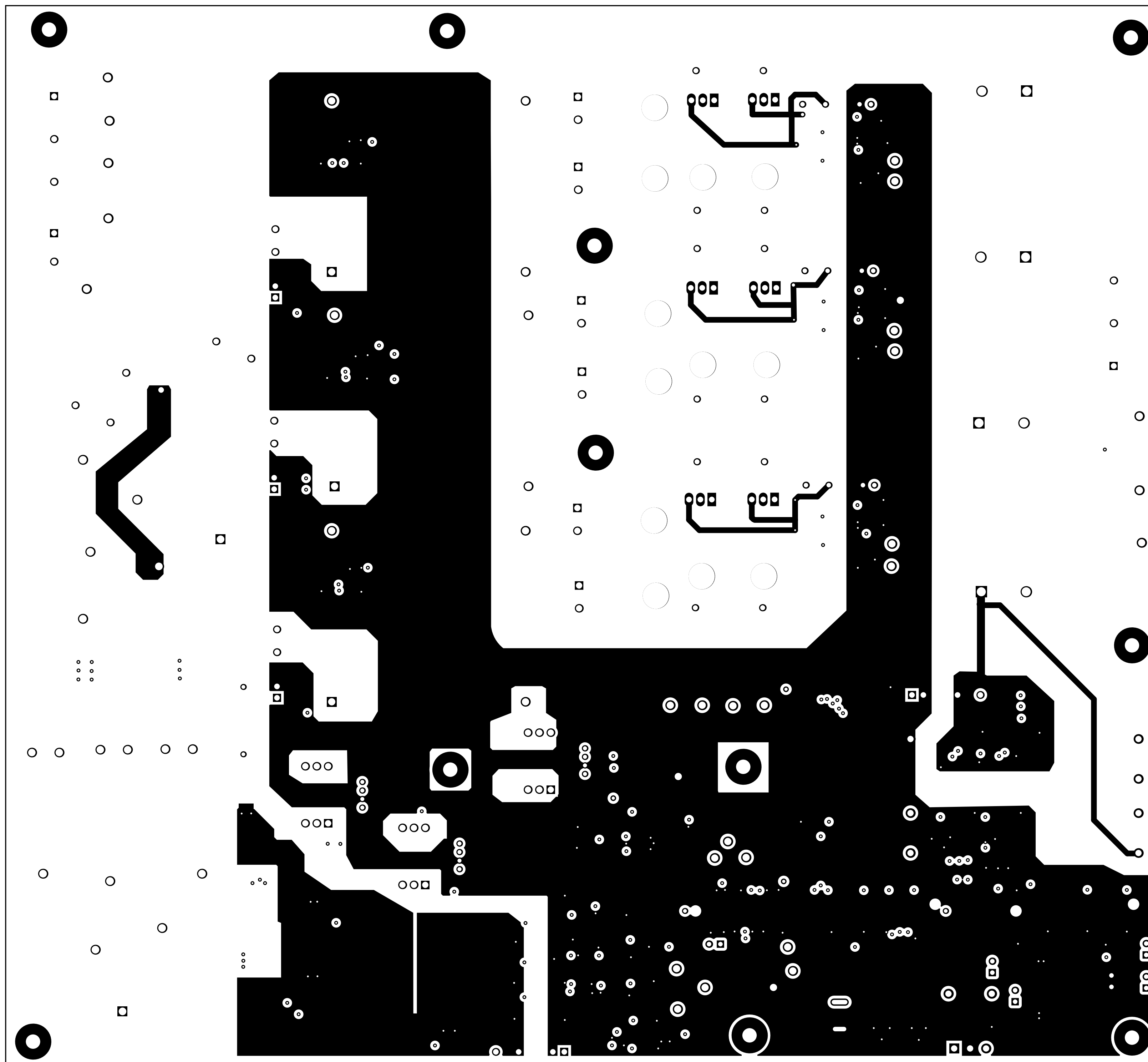
|                                  |                                  |        |                                |
|----------------------------------|----------------------------------|--------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: MCU011                  | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Top Overlay         | TID #: TIDM-1000                 |        |                                |
| PLOT NAME = Top Overlay          | GENERATED : 1/4/2018 10:14:38 AM |        | TEXAS INSTRUMENTS              |



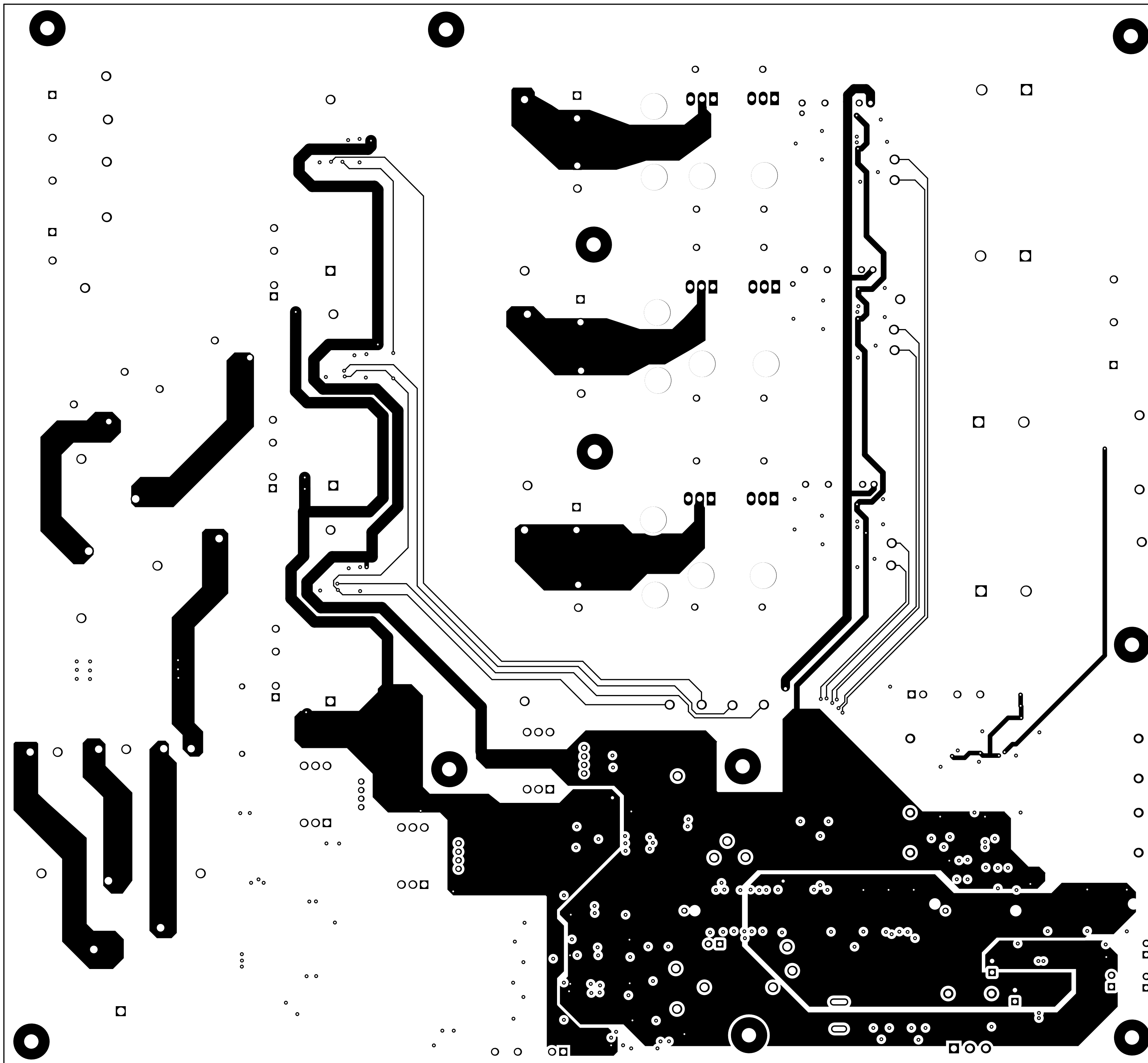
|                                  |                      |             |                                |
|----------------------------------|----------------------|-------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: MCU011      | REV: A      | SUN REV: Not In VersionControl |
| LAYER NAME = Top Solder          | TID #: TIDM-1000     |             |                                |
| PLOT NAME = Top Solder Mask      | GENERATED : 1/4/2018 | 10:14:39 AM | TEXAS INSTRUMENTS              |



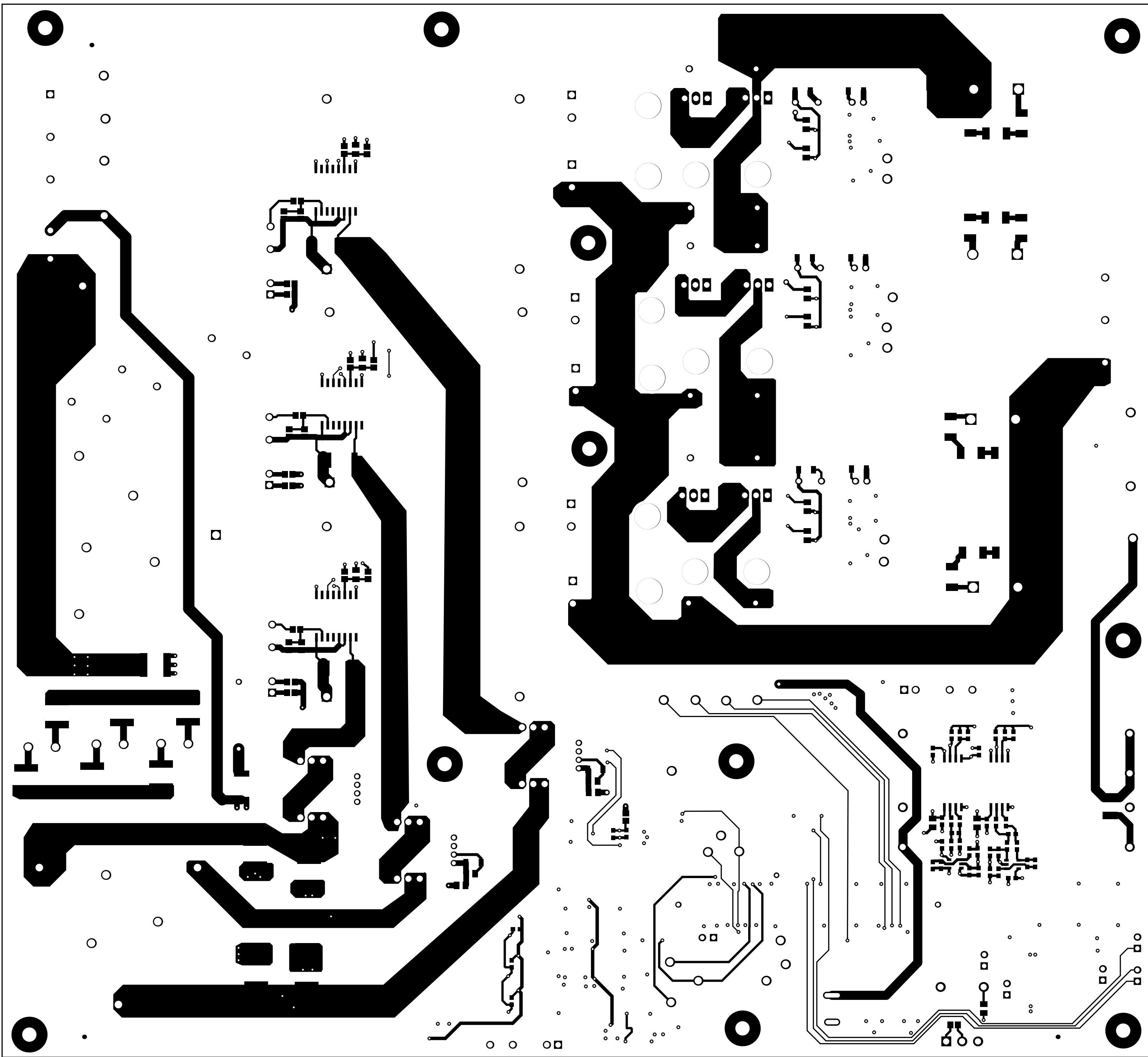
|                                  |                      |             |                                |
|----------------------------------|----------------------|-------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: MCU011      | REV: A      | SUN REV: Not In VersionControl |
| LAYER NAME = Top Layer           | TID #: TIDM-1000     |             |                                |
| PLOT NAME = Top Layer            | GENERATED : 1/4/2018 | 10:14:40 AM | TEXAS INSTRUMENTS              |



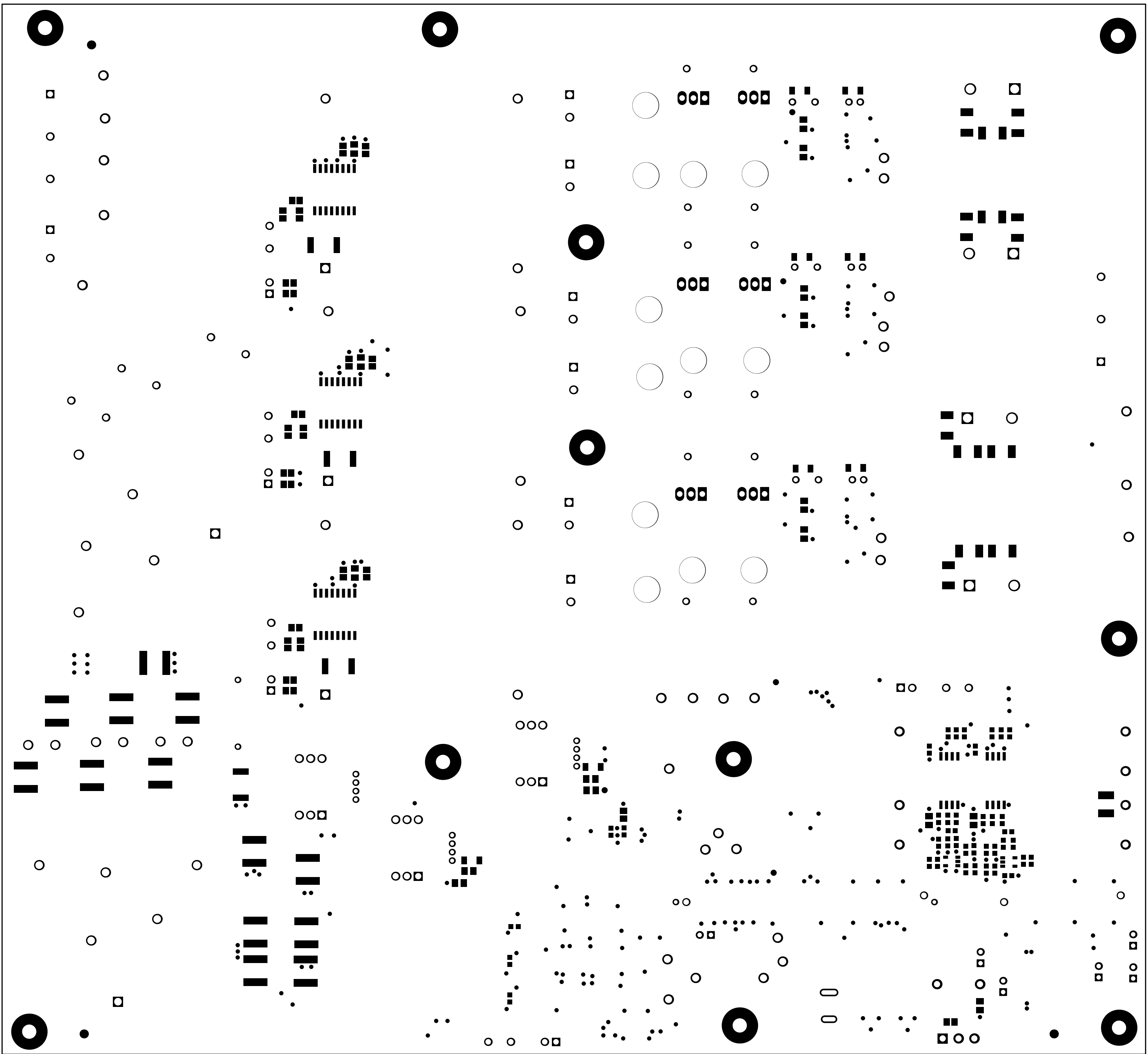
|                                  |                      |             |                                |
|----------------------------------|----------------------|-------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: MCU011      | REV: A      | SUN REV: Not In VersionControl |
| LAYER NAME =                     | TID #: TIDM-1000     |             |                                |
| PLOT NAME = Signal Layer 1       | GENERATED : 1/4/2018 | 10:14:42 AM | TEXAS INSTRUMENTS              |



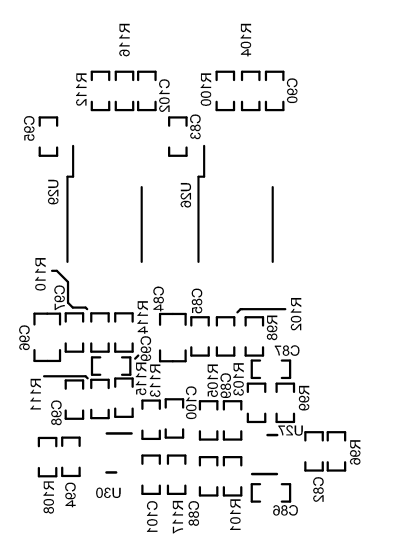
|                                  |                      |             |                                |
|----------------------------------|----------------------|-------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: MCU011      | REV: A      | SUN REV: Not In VersionControl |
| LAYER NAME =                     | TID #: TIDM-1000     |             |                                |
| PLOT NAME = Signal Layer 2       | GENERATED : 1/4/2018 | 10:14:43 AM | TEXAS INSTRUMENTS              |



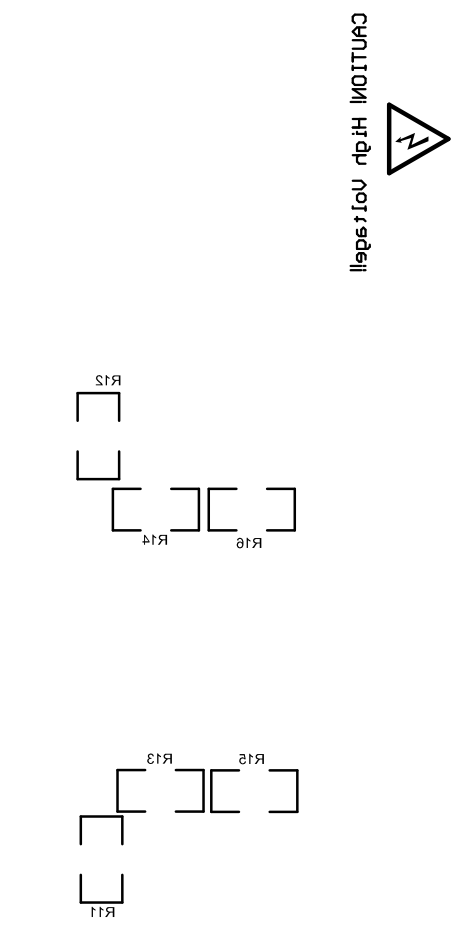
|                                  |                      |             |                                |
|----------------------------------|----------------------|-------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: MCU011      | REV: A      | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer        | TID #: TIDM-1000     |             |                                |
| PLOT NAME = Bottom Layer         | GENERATED : 1/4/2018 | 10:14:44 AM | TEXAS INSTRUMENTS              |



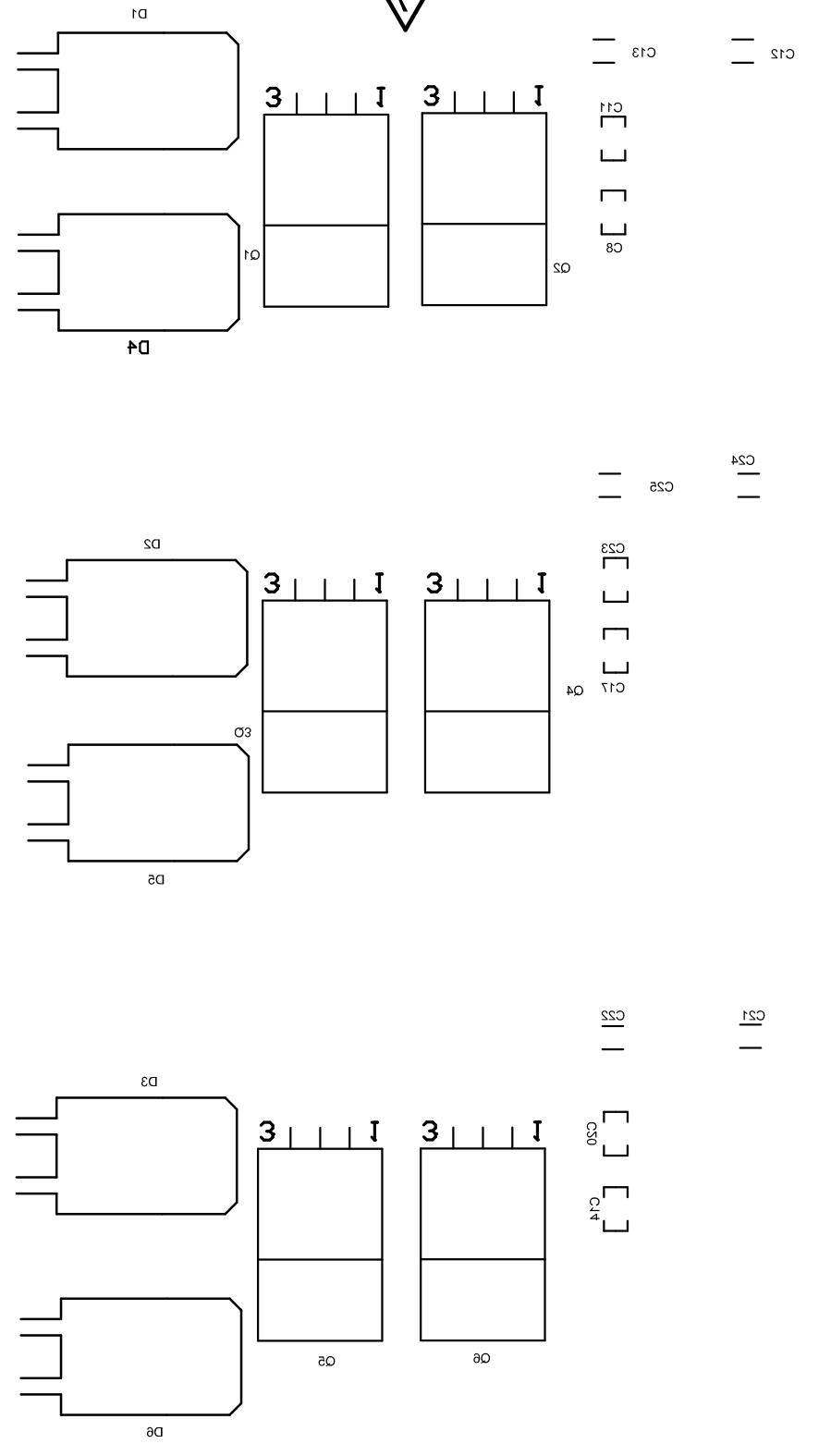
|                                  |                      |             |                                |
|----------------------------------|----------------------|-------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: MCU011      | REV: A      | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder       | TID #: TIDM-1000     |             |                                |
| PLOT NAME = Bottom Solder Mask   | GENERATED : 1/4/2018 | 10:14:46 AM | TEXAS INSTRUMENTS              |



L109  
C102

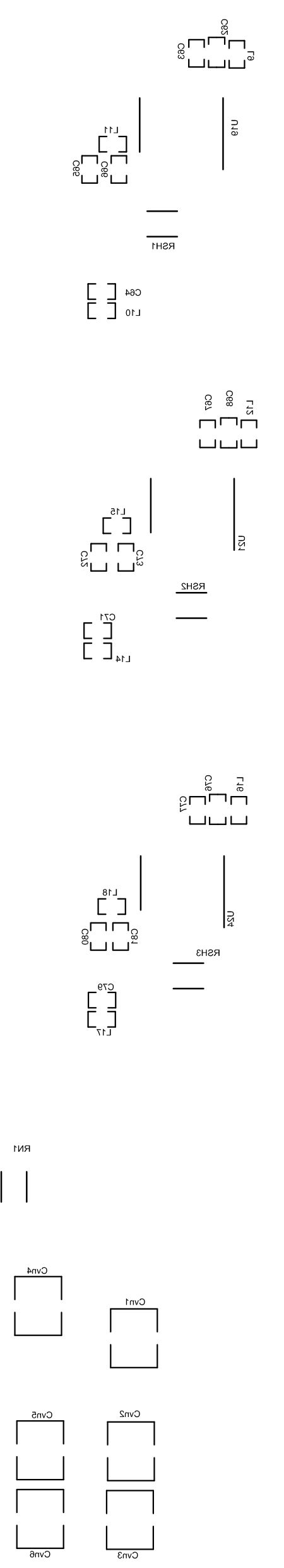


CAUTION High Voltage

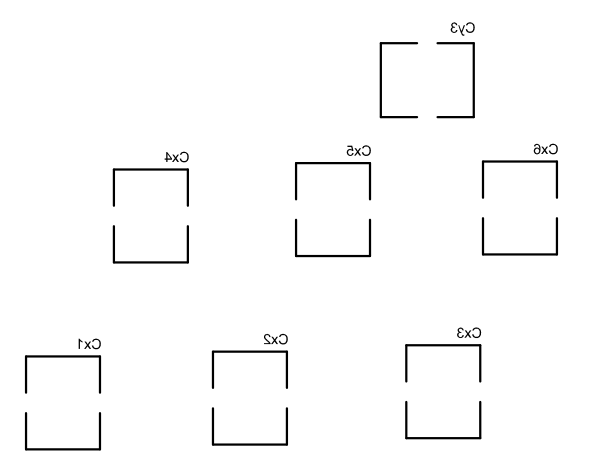


CAUTION High Voltage

C20  
C19  
C18



CAUTION High Voltage

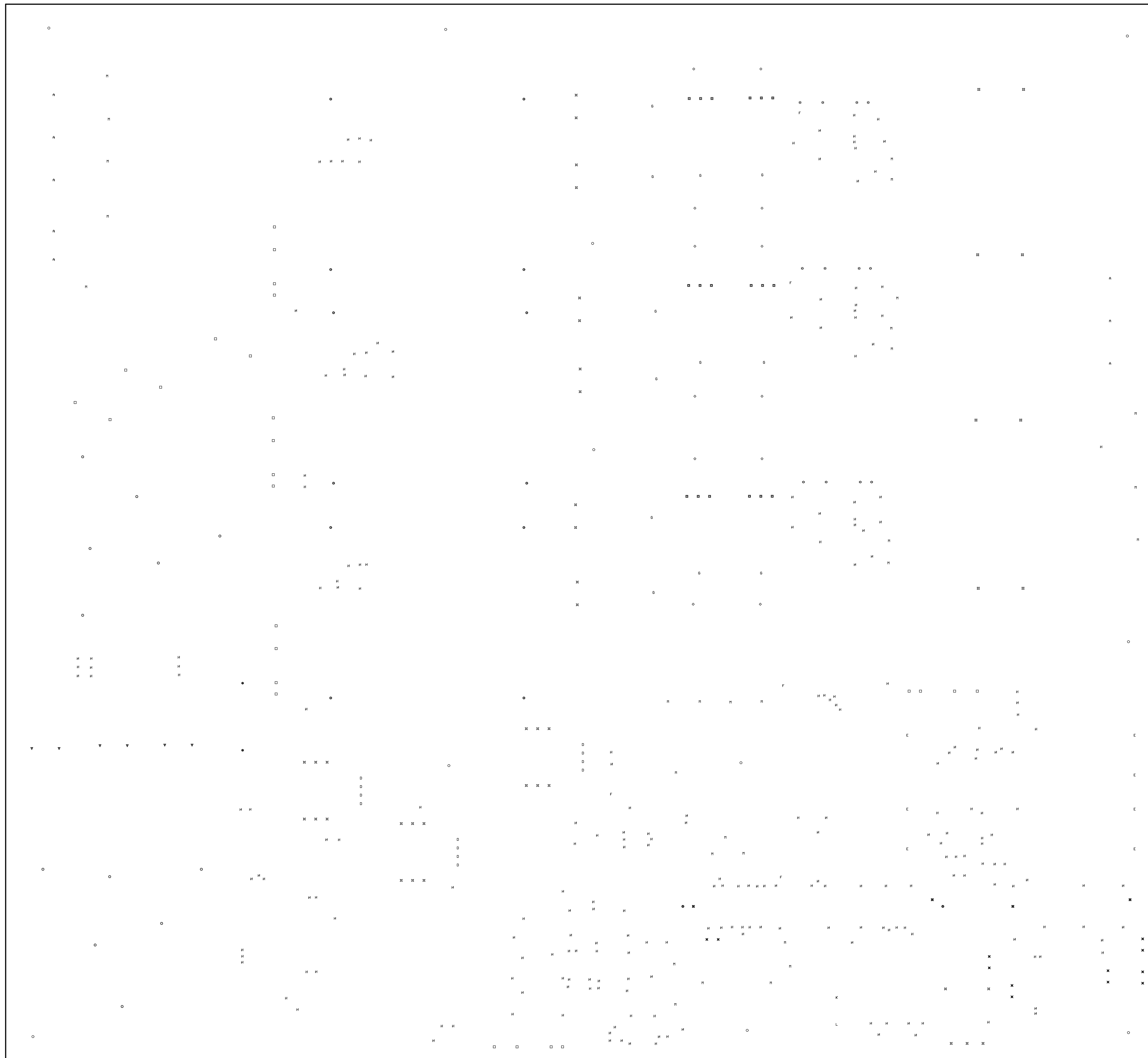


L108

L104

|                                  |                      |             |                                |
|----------------------------------|----------------------|-------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: MCU011      | REV: A      | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Overlay      | TID #: TIDM-1000     |             |                                |
| PLOT NAME = Bottom Overlay       | GENERATED : 1/4/2018 | 10:14:47 AM | TEXAS INSTRUMENTS              |

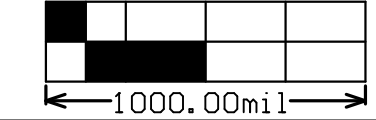
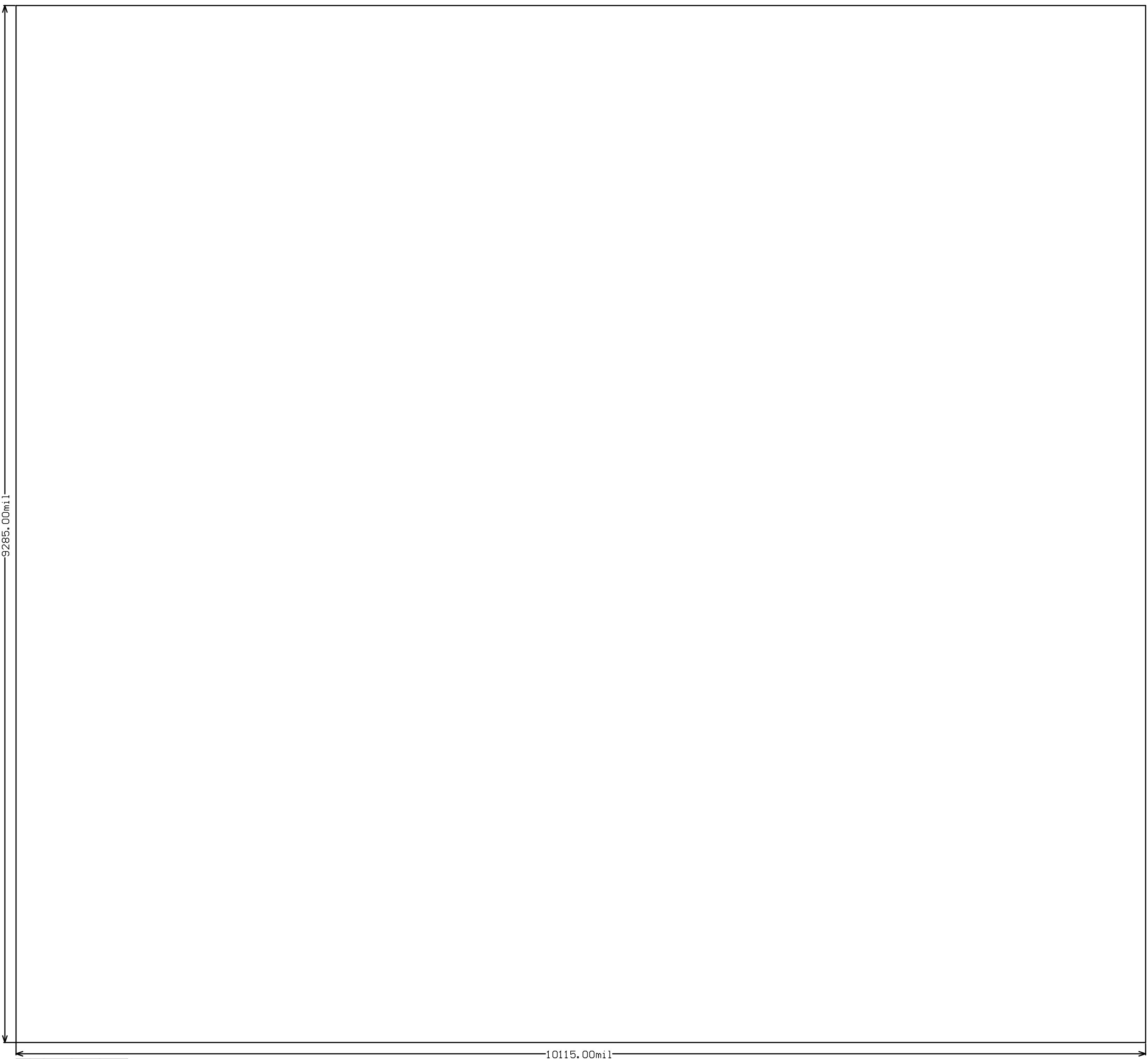




| Symbol | Quantity  | Finished Hole Size  | Plated | Hole Type | Drill Layer Pair         | Hole Tolerance |
|--------|-----------|---------------------|--------|-----------|--------------------------|----------------|
| ⊗      | 4         | 50.00mil (1.270mm)  | NPTH   | Round     | Top Layer - Bottom Layer |                |
| H      | 243       | 16.00mil (0.406mm)  | PTH    | Round     | Top Layer - Bottom Layer |                |
| F      | 5         | 28.00mil (0.711mm)  | PTH    | Round     | Top Layer - Bottom Layer |                |
| ⊕      | 2         | 33.07mil (0.840mm)  | PTH    | Round     | Top Layer - Bottom Layer |                |
| ⊛      | 2         | 33.47mil (0.850mm)  | PTH    | Round     | Top Layer - Bottom Layer |                |
| D      | 12        | 35.43mil (0.900mm)  | PTH    | Round     | Top Layer - Bottom Layer |                |
| ⊙      | 12        | 39.37mil (1.000mm)  | PTH    | Round     | Top Layer - Bottom Layer |                |
| ⊗      | 12        | 40.00mil (1.016mm)  | PTH    | Round     | Top Layer - Bottom Layer |                |
| ◇      | 12        | 43.31mil (1.100mm)  | PTH    | Round     | Top Layer - Bottom Layer |                |
| □      | 26        | 49.21mil (1.250mm)  | PTH    | Round     | Top Layer - Bottom Layer |                |
| ■      | 18        | 50.00mil (1.270mm)  | PTH    | Round     | Top Layer - Bottom Layer |                |
| ⌘      | 8         | 51.18mil (1.300mm)  | PTH    | Round     | Top Layer - Bottom Layer |                |
| E      | 7         | 55.00mil (1.397mm)  | PTH    | Round     | Top Layer - Bottom Layer |                |
| ⊗      | 35        | 55.12mil (1.400mm)  | PTH    | Round     | Top Layer - Bottom Layer |                |
| M      | 29        | 63.00mil (1.600mm)  | PTH    | Round     | Top Layer - Bottom Layer |                |
| ⊙      | 12        | 63.39mil (1.610mm)  | PTH    | Round     | Top Layer - Bottom Layer |                |
| ▽      | 6         | 64.96mil (1.650mm)  | PTH    | Round     | Top Layer - Bottom Layer |                |
| ⊕      | 12        | 66.93mil (1.700mm)  | PTH    | Round     | Top Layer - Bottom Layer |                |
| ⊗      | 8         | 78.74mil (2.000mm)  | PTH    | Round     | Top Layer - Bottom Layer |                |
| ⊙      | 11        | 125.98mil (3.200mm) | PTH    | Round     | Top Layer - Bottom Layer |                |
| G      | 12        | 230.00mil (5.842mm) | PTH    | Round     | Top Layer - Bottom Layer |                |
| L      | 1         | 39.37mil (1.000mm)  | PTH    | Slot      | Top Layer - Bottom Layer |                |
| K      | 1         | 39.37mil (1.000mm)  | PTH    | Slot      | Top Layer - Bottom Layer |                |
|        | 490 Total |                     |        |           |                          |                |

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.  
Hole Length = Routed Path Length + Tool Size + Slot length as defined in the PCB layout

|                                  |                      |             |                                |
|----------------------------------|----------------------|-------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: MCU011      | REV: A      | SUN REV: Not In VersionControl |
| LAYER NAME = Drill Drawing       | TID #: TIDM-1000     |             |                                |
| PLOT NAME = Drill Drawing        | GENERATED : 1/4/2018 | 10:14:48 AM | TEXAS INSTRUMENTS              |



|                                  |                                  |                   |                                |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: MCU011                  | REV: A            | SUN REV: Not In VersionControl |
| LAYER NAME = M2 Board Dimensions | TID #: TIDM-1000                 |                   |                                |
| PLOT NAME = Board Dimensions     | GENERATED : 1/4/2018 10:14:51 AM | TEXAS INSTRUMENTS |                                |

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